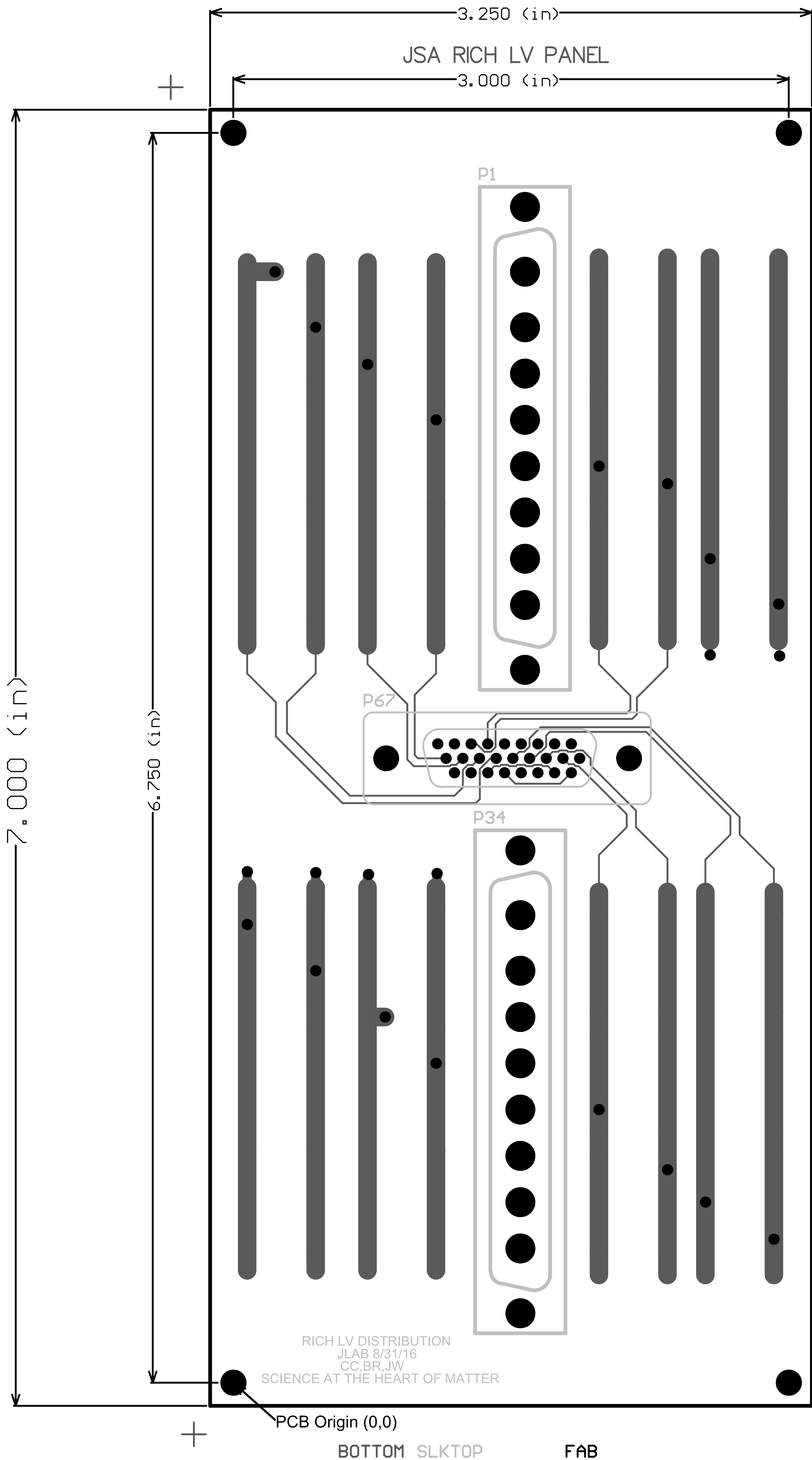




RICH LV PANEL CONTACT INFORMATION:
JEFF WILSON 757-269-7188

RICH LV PANEL SPECS:

1. 7.000" X 3.250", 0.062" THICK, FR-4 (Er=4.3), 2.0 oz. COPPER.
2. HOT AIR SOLDER LEVEL (HASL)
3. 2 LAYERS
4. SMOBC LPI GREEN.
5. 0.010 /0.008 MIN. TRACE/SPACE.
6. Front-to-Back Registration less than 0.004 .
7. Warp and Twist less than 0.007 per inch.
8. Permanent White Epoxy Silk-Screen.
9. LAYER STACK-UP (FR-4 with Dielectric Constant of 4.3)
10. Route and Singulate by board outline.

Lamination Thickness: 0.062 +/- .007
Over all Thickness: 0.067 +/- .007

TOP 2.0 oz. _____
BOT 2.0 oz. _____

○	22	30mil (0.762mm)	PTH	Round
▽	26	47.244mil (1.2mm)	PTH	Round
☆	4	110mil (2.794mm)	PTH	Round
⊕	2	122.047mil (3.1mm)	PTH	Round
✱	20	130mil (3.302mm)	PTH	Round
	74 Total			